Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0.5 is required to complete this declaration.

IPC-1752-2 v1.02 **1752-2**	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x	**Form Type *** **Distribute**	**Declaration Class *** **Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat**

Supplier Information

Company Name * **SPIL**	Company Unique ID SPIL	Unique ID Authority	**Response Date *** **2018-04-18**	Response Document ID	
Contact Name * **Technical Support**	Title - Contact Technical Support	**Phone - Contact *** **+1 408 879 5199**	**Email - Contact *** **Service Request**		
Authorized Representative * **Technical Support**	Title - Representative Technical Support	**Phone - Representative *** **+1 408 879 5199**	**Email - Representative** * **Service Request**	Supplier Comments or URL for Additional Information http://www.xilinx.com/support/techsup/tappingo.htm	

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight	UOM	Unit Type
XA_SFVB_SFVC784	XA_SFVB_SFVC784	Zynq UltraScale Plus (Flip-Chip		1.1		4.8767	g	Each
Alternate Recommendation				Alternate Item Comments				

Manufacturing Process Information

Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	Number of Reflow Cycles
Tin/Silver/Copper (Sn/Ag/Cu)	**Not Applicable**	**3**	**250** C	**30** seconds	**3**

Comments

*** Required Field**

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RoHS Material Composition Declaration

Declaration Type * **Custom**

RoHS Directive 2002/95/EC	**RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Xilinx certifies that the information provided hereunder is based on its available knowledge as of the date that Xilinx completes this form. This information is provided to assist Xilinx in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Xilinx acknowledges that its Suppliers may have relied on information provided by others and that Xilinx may not have independently verified such information. Upon request, Xilinx will make reasonable commercial efforts to obtain certifications from its suppliers where necessary. Notwithstanding any other agreements to the contrary, the information provided herein is provided solely for your reference on an "AS-IS" basis, and without warranty of any kind, express or implied. Xilinx hereby disclaims any and all liability associated with your use of this information.

RoHS Declaration *	3 - Item(s) does not contain RoHS restricted substances per the definition above except lead in solder and any other selected exemption(s)	Supplier Acceptance	**Accepted**

Exemptions: The items on this form meet the specifications of the RoHS Definition above, except for the following application-specific exemptions. Check the appropriate boxes below for the applicable exemptions for the item.

- ☐ **1**. Mercury in compact fluorescent lamps not exceeding 5 mg per lamp
- ☐ **2a.** Mercury in straight flourescent lamps for general purposes not exceeding 10 mg in halophosphate lamps
- ☐ **2b**. Mercury in straight flourescent lamps for general purposes not exceeding 5 mg in triphosphate lamps with a normal lifetime
- ☐ **2c**. Mercury in straight flourescent lamps for general purposes not exceeding 8 mg in triphosphate lamps with long lifetime
- ☐ **3**. Mercury in straight flourescent lamps for special purposes
- ☐ **4**. Mercury in other lamps not specifically mentioned in this list
- ☐ **5**. Lead in glass of cathode ray tubes, electronic components and flourescent tubes
- ☐ **6a**. Lead as an alloying element in steel containing up to 0.35% lead by weight
- ☐ **6b**. Lead as an alloying element in aluminum containing up to 0.4% lead by weight
- ☐ **6c.**. Lead as an alloying element in copper containing up to 4% lead by weight
- ☐ **7a**. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85 % by weight or more lead)
- ☐ **7b**. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications
- ☐ **7c**. Lead in electronic ceramic parts (e.g. piezoelectronic devices)
- ☐ **8.** Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC amending. Directive 76/769/EEC relating to restrictions on the marketing and use of certain dangerous substances
- ☐ **9.** Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators
- ☐ **10a**. DecaBDE in polymeric applications
- ☐ **10b.** Lead in lead-bronze bearing shells and bushes
- ☐ **11**. Lead used in compliant pin connector systems
- ☐ **12**. Lead as a coating material for a thermal conduction module c-ring
- ☐ **13a**. Lead in optical and filter glass
- ☐ **13b**. Cadmium in optical and filter glass
- ☐ **14.** Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight
- ☒ **15**. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages

Declaration Signature

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature		

*** Required Field**

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Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +P Inserts a New Part +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

	Item/SubItem Name		Homogeneous Material	Weight	Unit of Measure		Level	Substance Category		Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance -	Tolerance +	PPM
			Bump	7.167	mg		Supplier			Silver	7440-22-4		0.129	mg			17,999
							Supplier			Tin	7440-31-5		7.038	mg			982,00
			Capacitor 1	3.599	mg		Supplier			Copper	7440-50-8		0.5716	mg			158,83
							B	Nickel/Nickel Compou		Nickel	7440-02-0		0.019	mg			5,285.1
							B	Nickel/Nickel Compou		Nickel	7440-02-0		0.6467	mg			179,69
							Supplier			Tin	7440-31-5		0.0511	mg			14,186
							Supplier			Silicon Dioxide	7631-86-9		0.0501	mg			13,908
							Supplier			Barium Oxide	1304-28-5		1.3495	mg			374,96
							Supplier			Titanium dioxide	13463-67-7		0.6747	mg			187,48
							Supplier			boric oxide, diboron tri	1303-86-2		0.012	mg			3,337.9
							Supplier			5-sec-butyl-2-(2,4-dimet	-		0.2242	mg			62,308
			Heat sink	2.21	g		Supplier			Copper	7440-50-8		2.1735	g			983,49
							B	Nickel/Nickel Compou		Nickel	7440-02-0		36.465	mg			16,500
			Heat sink adhesi	55	mg		Supplier			4-Nonylphenol, branche	-		44	mg			800,00
							Supplier			Dimethyl siloxane, dim	68083-19-2		11	mg			200,00
			Silicon die	166.117	mg		Supplier			Silicon	7440-21-3		166.117	mg			1,000,(
			Solder ball	379.008	mg		Supplier			Copper	7440-50-8		1.895	mg			4,999.9
							Supplier			Silver	7440-22-4		11.37	mg			29,999
							Supplier			Tin	7440-31-5		365.743	mg			965,00
			Solder paste	9.299	mg		Supplier			Copper	7440-50-8		0.144	mg			15,485
							Supplier			Silver	7440-22-4		0.251	mg			26,992
							Supplier			Tin	7440-31-5		7.691	mg			827,07
							Supplier			Additives			1.213	mg			130,44

*** Required Field**

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Substrate	2.0185	g		Supplier			Copper	7440-50-8		1.1453	g			567,42
				Supplier			Silver	7440-22-4		0.404	mg			200.14
				Supplier			Tin	7440-31-5		12.312	mg			6,099.5
				Supplier			Resin			0.565	mg			279.91
				Supplier			Solder mask			25.433	mg			12,599
				Supplier			ABF			323.1623	mg			160,09
				Supplier			Core			511.2875	mg			253,30
Underfill	28	mg		Supplier			Carbon-Black	1333-86-4		0.28	mg			10,000
				Supplier			Silica, Vitreous	60676-86-0		16.2402	mg			580,00
				Supplier			(CHLOROMETHYL)OXII	25068-38-6		1.4001	mg			50,003
				Supplier			6-glycidyloxynapht-1-yl	27610-48-6		2.8002	mg			100,00
				Supplier			Bisphenol F/ epichlorol	9003-36-5		4.1993	mg			149,97
				Supplier			Additives			0.28	mg			10,000
				Supplier			Amine type hardener			2.8002	mg			100,00

*** Required Field**

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